

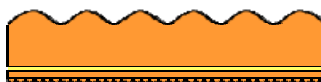
MT18Ex(C)

- MicroThin為附18 μm 載體銅箔的超薄銅箔。
MicroThin is ultra thin foil with 18 μm carrier foil.
- 最適用於線寬/線距(L/ S) =20/20~35/35之應用。
Usable for fine pitch pattern L/S=20/20 - 35/35 formation.
- 適用於無芯封裝基板的工藝。
Suitable for core-less process

用途/Application

- IC封裝載板
/Semiconductor Package
- 無芯封裝基板
/Core-less substrate

構成/Composition



生產地點/Production Site

- 日本 / Japan

代表性特性數據/Representive

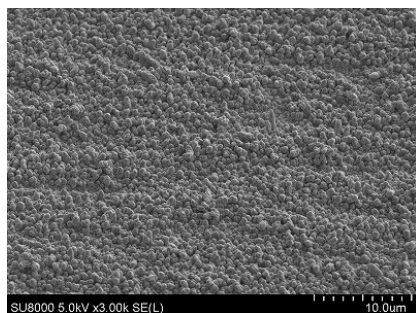
	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18Ex(C)	2	24	2	-	-	1.2
	3	33	2	-	-	1.2
	5	51	2	-	-	1.2

※上述表列為代表性數據非保證值

This is representative data, not guaranteed.

※Peel Strength為增鍍到35 μm 厚度之後的測試值
Evaluated after plated up to 35 μm .

處理面/Laminate side



阻劑面/ resist side

